molex

Part Number: 755860007

Product Description: 0.80mm Pitch, iPass I/O Surface Mount Receptacle, Right-Angle, External Application, 68 Circuit, 0.76µm Gold

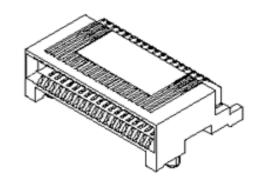
(Au)

Series Number: 75586

Status: Active

Product Category: High-Speed I/O

Connectors



Documents & Resources

Drawings

755860007_sd.pdf PK-75586-002-001.pdf PK-75586-101-001.pdf

3D Models and Design Files

755860007_stp.zip EE-75586-001-001.pdf SP-75586-001-001.zip

Specifications

AS-170432-0003-001.pdf AS-75586-001-001.pdf PS-75586-001-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	©
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2024)7663-DC (21 Jan 2025)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS

- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Active
Category	High-Speed I/O Connectors
Series	75586
Description	0.80mm Pitch, iPass I/O Surface Mount Receptacle, Right-Angle, External Application, 68 Circuit, 0.76µm Gold (Au)
Application	Wire-to-Board
Component Type	Receptacle
Product Name	iPass,Mini Multi-Lane,PCI Express
Туре	Pluggable
UPC	822348849550

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	0.5A
Data Rate	10.0 Gbps
Grounding to Panel	N/A
Shielded	No
Voltage - Maximum	30V AC (RMS)/DC

Boot Color	N/A
Circuits (Loaded)	68
Circuits (maximum)	68
Color - Resin	Black
Durability (mating cycles max)	250
Flammability	94V-0
Gender	Female
Keying to Mating Part	None
Lock to Mating Part	None
Material - Metal	High Performance Alloy (HPA)
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	1.000/g
Number of Rows	2
Orientation	Right Angle
Packaging Type	Embossed Tape on Reel
Panel Mount	No
PCB Locator	Yes
PCB Retention	None
PCB Thickness - Recommended	1.35mm
Pitch - Mating Interface	0.80mm
Pitch - Termination Interface	0.80mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Ports	1
Temperature Range - Operating	-40° to +80°C
Termination Interface Style	Surface Mount
Waterproof / Dustproof	No
Wire Insulation Diameter	N/A
Wire Size (AWG)	N/A

Solder Process Data

Max-Duration	20
Lead-Free Process Capability	REFLOW
Max-Cycle	1
Max-Temp	260

Use with Part(s)

Description	Part Number
External iPass Mini Multi-Lane SAS Guide Frames	74548

This document was generated on Mar 14, 2025